


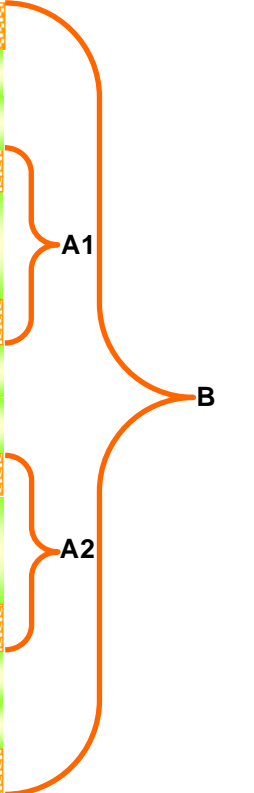
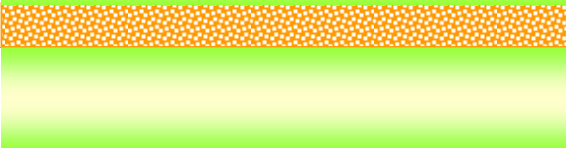
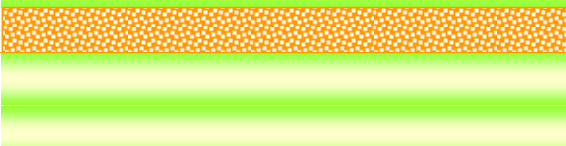

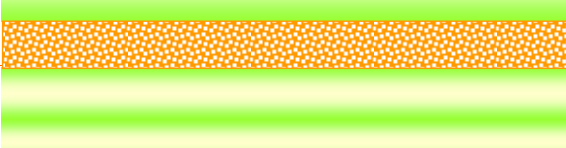

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**06 159 FR4 55 L41.35 P10\_06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_159\_FR4\_55\_L41.35\_p10\_06**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	55 $\mu$	Copper			
	60 $\mu$	Prepreg			(60 $\mu$ PrePreg-Type: 1080)
	100 $\mu$	Prepreg			(100 $\mu$ PrePreg-Type: 2125)
<b>Layer-2</b>	35 $\mu$	Copper			A1
	410 $\mu$	L-FR4			
<b>Layer-3</b>	35 $\mu$	Copper			B
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-4</b>	35 $\mu$	Copper			A2
	410 $\mu$	L-FR4			
<b>Layer-5</b>	35 $\mu$	Copper			
	100 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
<b>Layer-99</b>	55 $\mu$	Copper			

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